



Product Change Notification / RMES-09ZZXT280

Date:

25-Feb-2021

Product Category:

32-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4523 and 4523.001 Initial Notice: Qualification of MTAI as an additional assembly site for selected ATSAMC20xx, ATSAMC21xx, ATSAMD20xx, ATSAMD21xx and ATSAMDA1xx device families available in 48L VQFN packages.

Affected CPNs:

[RMES-09ZZXT280_Affected_CPN_02252021.pdf](#)

[RMES-09ZZXT280_Affected_CPN_02252021.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MTAI as an additional assembly site for selected ATSAMC20xx, ATSAMC21xx, ATSAMD20xx, ATSAMD21xx and ATSAMDA1xx device families available in 48L VQFN package.

Pre Change: For wettable flank products:

Assembled at ASCL using gold (Au) bond wire, 8600 die attach, G700 molding compound material with 210 x 210 mils paddle size without locking holes leadframe.**or**

Assembled at NSEB using gold (Au) or palladium coated copper wire with gold flash (CuPdAu) bond wire, EN-4900G or ATB-125 die attach, G700 molding compound material with 208 x 208 mils paddle size without locking holes leadframe.

or

Assembled at MMT using gold (Au) bond wire, 3280 die attach, G700 molding compound material with 217 x 217 mils paddle size with locking holes leadframe.

For non-wettable flank products: Assembled at ASE using palladium coated copper wire with gold flash (CuPdAu) or palladium coated copper (PdCu) bond wire, EN-4900F die attach, G631H molding compound and C7025 leadframe material with 217 x 217 mils paddle size without locking holes.

or

Assembled at ASCL using palladium coated copper wire with gold flash (CuPdAu) bond wire, EN-4900GC die attach, G700 molding compound and C194 leadframe material with 210 x 210 mils paddle size without locking holes. **or**

Assembled at MMT using gold (Au) bond wire, 3280 die attach, G700 molding compound and C194 leadframe material with 217 x 217 mils paddle size with locking holes leadframe.

Post Change: For wettable flank products:

Assembled at ASCL using gold (Au) bond wire, 8600 die attach, G700 molding compound material with 210 x 210 mils paddle size without locking holes leadframe.

or

Assembled at NSEB using gold (Au) or palladium coated copper wire with gold flash (CuPdAu) bond wire, EN-4900G or ATB-125 die attach, G700 molding compound material with 208 x 208 mils paddle size without locking holes leadframe.

or

Assembled at MMT using gold (Au) bond wire, 3280 die attach, G700 molding compound material with 217 x 217 mils paddle size with locking holes leadframe.

or

Assembled at MTAI using gold (Au) bond wire, 3280 die attach, G700 molding compound material with 217 x 217 mils paddle size with locking holes leadframe.

For non-wettable flank products: Assembled at ASE using palladium coated copper wire with gold flash (CuPdAu) or palladium coated copper (PdCu) bond wire, EN-4900F die attach, G631H molding compound and C7025 leadframe material with 217 x 217 mils paddle size without locking holes.

or

Assembled at ASCL using palladium coated copper wire with gold flash (CuPdAu) bond wire, EN-4900GC die attach, G700 molding compound and C194 leadframe material with 210 x 210 mils paddle size without locking holes.

or

Assembled at MMT using gold (Au) bond wire, 3280 die attach, G700 molding compound and C194 leadframe material with 217 x 217 mils paddle size with locking holes leadframe.

or

Assembled at MTAI using gold (Au) bond wire, 3280 die attach, G700 molding compound and C194 leadframe material with 217 x 217 mils paddle size with locking holes leadframe.

Pre and Post Change Summary:

For wettable flank products:

	Pre Change			Post Change			
Assembly Site	ASE Group Chung-Li (ASCL)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Microchip Technology Thailand (Branch) / (MMT)	ASE Group Chung-Li (ASCL)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Microchip Technology Thailand (Branch) / (MMT)	Microchip Technology Thailand (HQ) (MTAI)
Wire material	Au	Au or CuPdAu	Au	Au	Au or CuPdAu	Au	Au

Final PCN Issue Date									X
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Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 25, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_RMES-09ZZXT280_Pre and Post Change Summary.pdf](#)

[PCN_RMES-09ZZXT280_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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